TOSHIBA Photocoupler GaAs Ired & Photo-Thyristor

TLP741G

Office Machine
Household Use Equipment
Solid State Relay
Switching Power Supply

The TOSHIBA TLP741G consists of a photo-thyristor optically coupled to a gallium arsenide infrared emitting diode in a six lead plastic DIP package.

- Peak off-state voltage: 400V(min.)
- Trigger LED current: 10mA(max.)
- On-state current: 150mA(max.)
- UL recognized: UL1577, file no. E67349
- BSI approved: BS EN60065: 1994

Certificate no. 6617 BS EN60950: 1992 Certificate no. 7366

- Isolation voltage: 4000V_{rms}(min.)
- Option (D4) type

VDE approved: DIN VDE0884/08, 87

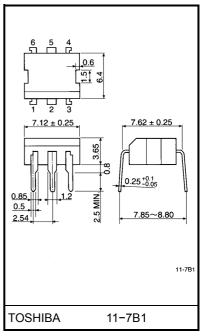
Certificate no. 65640

Maximum operating insulation voltage: 630 VPK Highest permissible over voltage: 6000 VPK

(Note) When a VDE0884 approved type is needed, please designate the "option (D4)"

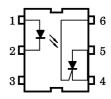
		2mm pich ndard type	10.16mm pich (LF2) type
• Creepage dist	7.0	mm(min.)	8.0mm(min.)
Clearance:		mm(min.)	8.0mm(min.)
Insulation thi		mm(min.)	0.5mm(min.)

Unit in mm



Weight: 0.35 g

Pin Configuration (top view)



1 : ANODE 2 : CATHODE

3: NC

4 : CATHODE 5 : ANODE 6 : GATE



Maximum Ratings (Ta = 25°C)

	Characteristic	Symbol	Rating	Unit	
	Forward current	IF	60	mA	
	Forward current derating (Ta ≥ 39°C)	ΔI _F / °C	-0.7	mA / °C	
	Peak forward current (100µs pulse, 100pps)	I _{FP}	1	Α	
LED	Power dissipation	P _D	100	mW	
	Power dissipation derating (Ta ≥ 25°C)	ΔP _D / °C	-1.0	mW / °C	
	Reverse voltage	V _R	5	V	
	Junction temperature	Tj	125	°C	
	Peak forward voltage($R_{GK} = 27k\Omega$)	V_{DRM}	400	V	
	Peak reverse voltage(R _{GK} = 27kΩ)	V_{RRM}	400	V	
	On-state current	I _{T(RMS)}	150	mA	
	On–state current derating (Ta ≥ 25°C)	ΔI _T / °C	-2.0	mA / °C	
Detector	Peak on-state current (100µs pulse, 120pps)	I _{TP}	3	Α	
Dete	Peak one cycle surge current	I _{TSM}	2	Α	
	Peak reverse gate voltage	V_{GM}	5	V	
	Power dissipation	P _D	150	mW	
	Power dissipation derating (Ta ≥ 25°C)	ΔP _D / °C	-2.0	mW / °C	
	Junction temperature	Tj	100	°C	
Storage temperature range		T _{stg}	-55~125	°C	
Operating temperature range		T _{opr}	-55~100	°C	
Lead soldering temperature (10s)		T _{sol}	260	°C	
Total package power dissipation		PT	250	mW	
Total package power dissipation derating (Ta ≥ 25°C)		ΔP _T / °C	-3.3	mW / °C	
Isolatio	on voltage (AC, 1 min., R.H. ≤ 60%)	BVS	4000	V _{rms}	

Recommended Operating Conditions

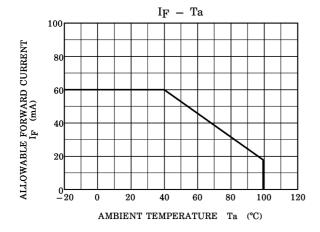
Characteristic	Symbol	Min.	Тур.	Max.	Unit
Supply voltage	V_{AC}	_	_	120	V _{ac}
Forward current	I _F	15	20	25	mA
Operating temperature	T _{opr}	-25	_	85	°C
Gate to cathode resistance	R _{GK}	_	27	33	kΩ
Gate to cathode capacity	C _{GK}	_	0.01	0.1	μF

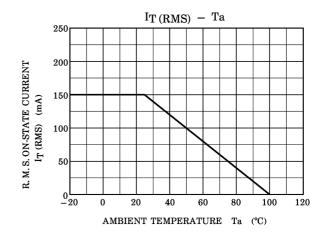
Individual Electrical Characteristics (Ta = 25°C)

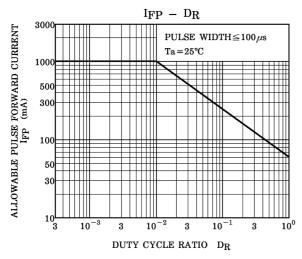
	Characteristic	Symbol	Test Condition		Min.	Тур.	Max.	Unit
	Forward voltage	V _F	I _F = 10mA		1.0	1.15	1.3	V
LED	Reverse current	I _R	V _R = 5V		_	_	10	μΑ
	Capacitance	C _T	V = 0, f = 1MHz		_	30	_	pF
Detector	Off-state current	I _{DRM}	V _{AK} = 400V R _{GK} = 27kΩ	Ta = 25°C	_	10	5000	nA
				Ta = 100°C	_	1	100	μΑ
	Reverse carrent	I _{RRM}	V _{KA} = 400V R _{GK} = 27kΩ	Ta = 25°C	_	10	5000	nA
				Ta = 100°C	_	1	100	μA
	On-state voltage	V _{TM}	I _{TM} = 100mA		_	0.9	1.3	V
	Holding current	lΗ	R _{GK} = 27kΩ		_	0.2	_	mA
	Off–state dv / dt	dv/dt	$V_D = 280V, R_{GK} = 27k\Omega$		5	10	_	V/µs
	Capacitance C _j V =	C.	V = 0, f = 1MHz	Anode to gate	_	20	_	pF
		V = 0, 1 = 11VIFIZ	Gate to cathode	_	350	_	PΓ	

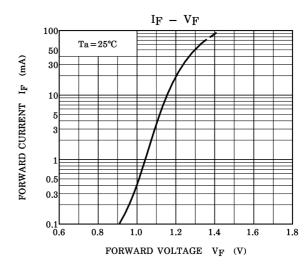
Coupled Characteristics (Ta = 25°C)

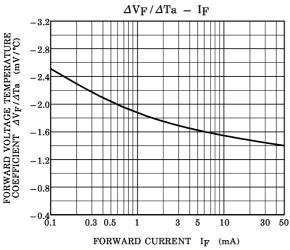
Characteristic	Symbol	Test Condition	Min.	Тур.	Max.	Unit	
Trigger LED current	I _{FT}	V_{AK} = 6V, R_{GK} = 27k Ω	_	4	10	mA	
Turn-on time	ton	$I_F = 30$ mA, $V_{AA} = 50$ V, $R_{GK} = 27$ k Ω	_	10	_	μs	
Coupled dv/dt	dv/dt	V_S = 500V, R_{GK} = 27k Ω	500	_	_	V/µs	
Capacitance (input to output)	CS	V _S = 0, f = 1MHz	_	0.8	_	pF	
Isolation resistance	R _S	V _S = 500V	1×10 ¹²	10 ¹⁴	_	Ω	
	BVS	AC, 1 minute	4000	_	_	V	
Isolation voltage		AC, 1 second, in oil	_	10000	_	V _{rms}	
		DC, 1 minute, in oil	_	10000	_	V _{dc}	

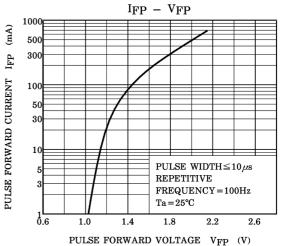




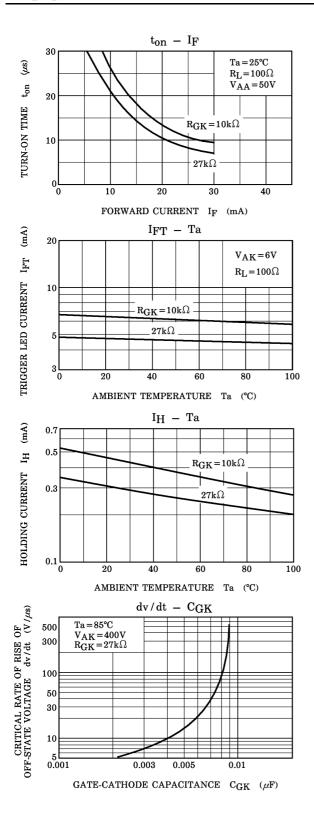


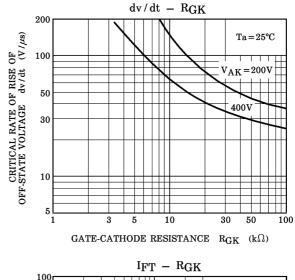


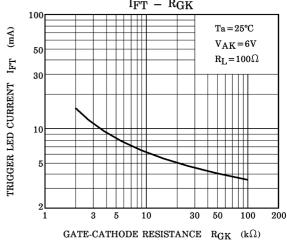


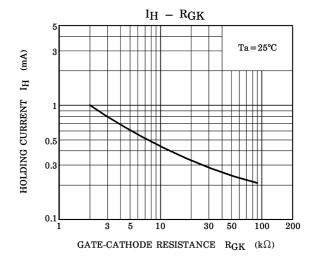


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